IN THE SPECIFICATION

Please amend the specification on page 18, lines 5-24, as follows:

The metrology tool 1010 may be any of a variety of devices used to measure electrical and/or structural features on the wafer 1002 after being processed by the tools 1004-1009. For example, the metrology tool 1010 may be configured to measure feature sizes on the wafer 1002, such as the thickness of the copper layer, and provide the measurement data to the controller 1012. Measurements of this type may be useful in determining whether the electroplating process has produced a layer of copper having a desired thickness, and then modifying the operation of the electroplate tool 1009, if necessary, so that subsequently processed wafers 1002 have the desired thickness. ~~Such a metrology tool is available from Rudolph Technolgies as model number 200, Tencor as Model NC110, or the like.~~ It is contemplated that in some embodiments of the instant invention additional tools (not shown) may be deployed in the manufacturing line, such as additional metrology tools 1010 positioned to measure certain mechanical or electrical parameters of the wafer 1002 at various steps in the manufacturing process. Alternatively, additional tools may be deployed intermediate the etcher 1007 and the electroplate tool 1009. These intermediate devices may perform additional processes, such as cleaning, rinsing, forming additional layers, etc. Moreover, it is anticipated that the formation of some of the features on the wafer 1002 will be produced by operations performed by the tools 1004-1009 other than in the order illustrated. For example, it may be useful to route the wafer 1002 through the photolithography tool 1004, stepper 1006 and etcher 1007 a plurality of times before delivering the wafer 1002 to the electroplate tool 1009.

Please delete the entire paragraph beginning at the bottom of page 20, line 2 through page 21, line 6, as follows:

~~An exemplary software system capable of being adapted to perform the functions of the automatic process controller 1012, as described, is the KLA-Tencor Catalyst system offered by KLA-Tencor, Inc. The KLA-Tencor Catalyst system uses Semiconductor Equipment and Materials International (SEMI) Computer Integrated Manufacturing (CIM) Framework compliant system technologies, and is based on the Advanced Process Control (APC) Framework. CIM (SEMI E81-0699 – Provisional Specification for CIM Framework Domain Architecture) and APC (SEMI E93-0999 - Provisional Specification for CIM Framework Advanced Process Control Component) specifications are publicly available from SEMI.~~